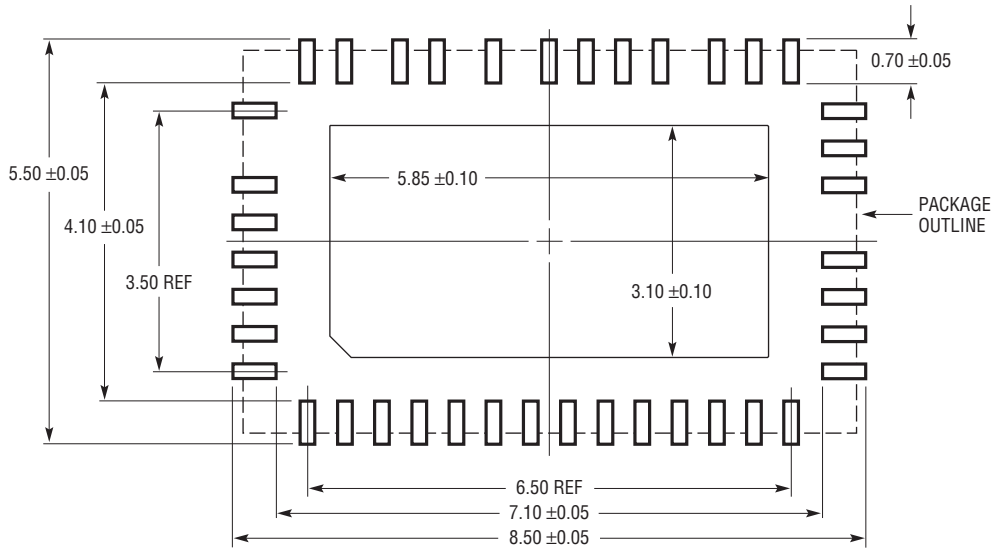
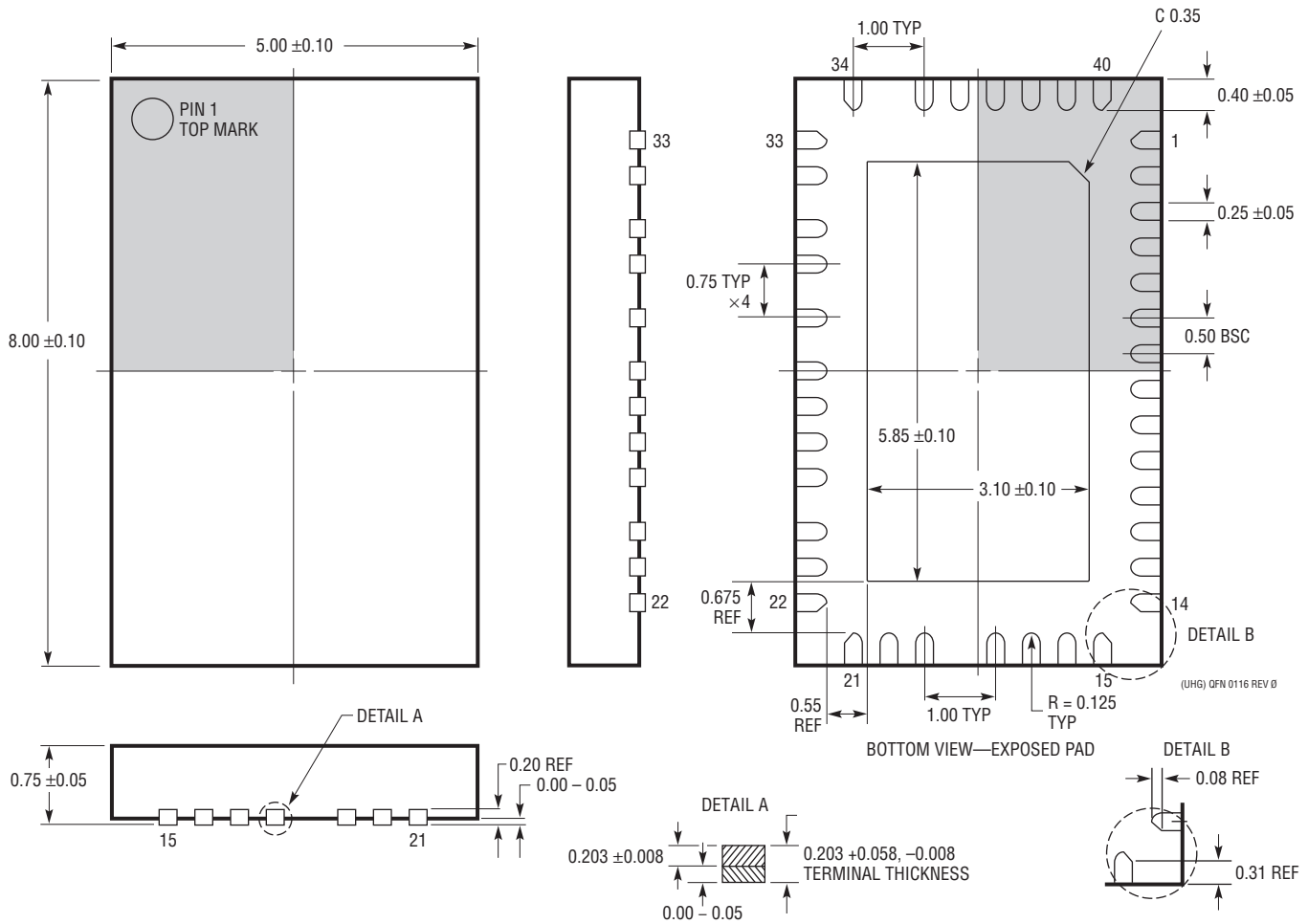


**UHG Package**  
**40-Lead Plastic QFN (5mm × 8mm)**  
 (Reference LTC DWG # 05-08-1528 Rev 0)



RECOMMENDED SOLDER PAD PITCH AND DIMENSIONS  
APPLY SOLDER MASK TO AREAS THAT ARE NOT SOLDERED



NOTE:

1. ALL DIMENSIONS ARE IN MILLIMETERS. ANGLES IN DEGREES.
2. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.  
COPLANARITY SHALL NOT EXCEED 0.08MM.
3. WARPAGE SHALL NOT EXCEED 0.10MM.

4. PACKAGE LENGTH / PACKAGE WIDTH ARE CONSIDERED AS SPECIAL CHARACTERISTIC(S).  
5. REFER JEDEC MO-220.